

View Online at https://aerobasegroup.com/nsn/5910-01-369-6373

Body Style: Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.001 **Terminal Length:** 0.5 millimeters **Body Length:** 2.0 millimeters **Body Width:** 1.25 millimeters **Body Height:** 1.3 millimeters Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 100.0 megohm-microfarads **Capacitance Value Per Section:** 3300.000 picofarads single section Voltage Tempurature Limits Per Section In Percent Capacitance Change: -15.0/+15.0 with rated voltage applied single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Nonderated Continuous Voltage Rating And Type Per Section: 100.0 dc single section **Tolerance Range Per Section:** -10.00/+10.00 percent single section **Case Material:** Ceramic Insulation Resistance At Reference Temp: 1000.0 megohm-microfarads **Dissipation Factor At Reference Tempurature In Percent:** 2.500 **Terminal Surface Treatment:** Solder **Test Data Document:** 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.). **Terminal Type And Quantity:**

2 bonding pad

Specification Data:

81349-mil-c-55681/7 government specification



Shelf Life:

N/a

Unit Of Measure:

Demilitarization:

No

Fiig:

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